Technical Datasheet Elecolit® 3647



Product Description

Modified epoxy | 1 part | solvent-free | thermal-curing | thermally conductive | electrically conductive

- Die attach
- Conductive bonding

- Very flexible
- Good adhesion to glass, various metals and plastics

Curing Properties

This adhesive must be cured with heat. Typical curing temperatures are listed in the table below.

Temperatures	Time
100°C	8 min
120°C	3 min
150°C	90 s

The heat cure times are only provided as a guideline. They are derived from curing a 2g adhesive sample without affixed substrates in a laboratory environment. Actual cure times can vary based on part size, configuration, adhesive volume and temperature control required for the component substrates to attain oven temperature.

The final bond strength of the adhesive is achieved no sooner than 24 h after the bonded components are removed from the oven.

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Resin	Technical Data	
Appearance Grey Filler Silver		
Filler Silver Sil	Resin	, ,
Filler - weight [%] 80 Particle size D90 [µm] 21.8 Uncured Material Viscosity [mPas] (Kinexus Rheometer, 25 °C, 10s²) 7,000 – 12,000 PE-Standard 064 3.7 – 3.9 PE-Standard 064 9		-
Particle size D90 [µm] 21.8		Silver
Uncured Material	Filler - weight [%]	80
Viscosity [mPas] (Kinexus Rheometer, 25 °C, 10s¹) 7,000 − 12,000 PE-Standard 064 2 − 3 Density [g/cm³] 3.7 − 3.9 PE-Standard 004 24 Working life [h] 24 @ room temperature 24 Cured Material 70 − 85 Hardness shore A 120°C, 30min 70 − 85 PE-Standard 006 −40 − 180 Linear shrinkage [%] <0.5	Particle size D90 [μm]	21.8
Viscosity [mPas] (Kinexus Rheometer, 25 °C, 10s¹) 7,000 − 12,000 PE-Standard 064 2 − 3 Density [g/cm³] 3.7 − 3.9 PE-Standard 004 24 Working life [h] 24 @ room temperature 24 Cured Material 70 − 85 Hardness shore A 120°C, 30min 70 − 85 PE-Standard 006 −40 − 180 Linear shrinkage [%] <0.5	Uncured Material	
### PE-Standard 064 Thixotropic index [1/10] 2 - 3 Density [g/cm³] 3.7 - 3.9 PE-Standard 004 2 - 3 Density [g/cm³] 3.7 - 3.9 Working life [h] 24 Working life [h] 24 Working life [h] 24 Working life [h] 25 Working life [h] 26 Working life [h] 26 Working life [h] 26 Working life [h] 27 Working life [h. Working life [h. Working life [h. Work		
PE-Standard 064 Density [g/cm³] PE-Standard 004 Working life [h]		7,000 – 12,000
PE-Standard 064 Density [g/cm³] PE-Standard 004 Working life [h]	Thixotropic index [1/10]	2 2
## PE-Standard 004 Working life [h]	,	2-3
### PE-Standard 004 Working life [h] @ room temperature	Density [g/cm³]	27 20
### Cured Material ### Hardness shore A ### 120°C, 30min ### 20°C, 30min ### 30 – 90 ### 30 – 9	PE-Standard 004	3.7 – 3.9
© room temperature Cured Material Hardness shore A 70 − 85 20°C, 30min 70 − 85 PE-Standard 006 −40 − 180 Linear shrinkage [%] <0.5	Working life [h]	24
Hardness shore A 120°C, 30min PE-Standard 006 Temperature resistance [°C] Linear shrinkage [%] Linear shrinkage [%] 120°C, 30min Water absorption [wt%] 120°C, 30min PE-Standard 016 Glass transition temperature - DSC [°C] 120°C, 30min Coefficient of thermal expansion [ppm/K] below Tg 120°C, 30min PE-Standard 017 Coefficient of thermal expansion [ppm/K] above Tg 120°C, 30min PE-Standard 017 Thermal conductivity [W/m*K] 120°C, 30min PE-Standard 017 Thermal conductivity [W/m*K] 120°C, 30min 1×10°4-3×10°4 PE-Standard 062 Volume resistivity [Ohm*cm] 120°C, 30min 1×10°4-3×10°4 PE-Standard 040 Storage modulus – DMA [MPa] 120°C, 30min 120°C, 30min		24
Hardness shore A 120°C, 30min PE-Standard 006 Temperature resistance [°C] Linear shrinkage [%] Linear shrinkage [%] 120°C, 30min Vater absorption [wt%] 120°C, 30min PE-Standard 016 Glass transition temperature - DSC [°C] 120°C, 30min Coefficient of thermal expansion [ppm/K] below Tg 120°C, 30min PE-Standard 017 Coefficient of thermal expansion [ppm/K] above Tg 120°C, 30min PE-Standard 017 Thermal conductivity [W/m*K] 120°C, 30min PE-Standard 017 Thermal conductivity [W/m*K] 120°C, 30min 120°C, 30min 1 × 10°4 – 3 × 10°4 PE-Standard 040 Storage modulus – DMA [MPa] 120°C, 30min 120°C, 30min	Cured Material	
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Temperature resistance [°C]	120°C, 30min	70 – 85
Linear shrinkage [%] 120°C, 30min	PE-Standard 006	
120°C, 30min	Temperature resistance [°C]	-40 – 180
Water absorption [wt%] 120°C, 30min PE-Standard 016 Glass transition temperature - DSC [°C] 120°C, 30min PE-Standard 009 Coefficient of thermal expansion [ppm/K] below Tg 120°C, 30min PE-Standard 017 Coefficient of thermal expansion [ppm/K] above Tg 120°C, 30min PE-Standard 017 Thermal conductivity [W/m*K] 120°C, 30min PE-Standard 062 Volume resistivity [Ohm*cm] 120°C, 30min PE-Standard 062 Storage modulus – DMA [MPa] 120°C, 30min	Linear shrinkage [%]	
Water absorption [wt%] 120°C, 30min PE-Standard 016 Glass transition temperature - DSC [°C] 120°C, 30min PE-Standard 009 Coefficient of thermal expansion [ppm/K] below Tg 120°C, 30min PE-Standard 017 Coefficient of thermal expansion [ppm/K] above Tg 120°C, 30min PE-Standard 017 Thermal conductivity [W/m*K] 120°C, 30min PE-Standard 062 Volume resistivity [Ohm*cm] 120°C, 30min PE-Standard 040 Storage modulus – DMA [MPa] 120°C, 30min 120°C, 30min 120°C, 30min 120°C, 30min	120°C, 30min	<0.5
120°C, 30min		
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Glass transition temperature - DSC [°C] 120°C, 30min PE-Standard 009 Coefficient of thermal expansion [ppm/K] below Tg 120°C, 30min PE-Standard 017 Coefficient of thermal expansion [ppm/K] above Tg 120°C, 30min PE-Standard 017 Thermal conductivity [W/m*K] 120°C, 30min PE-Standard 062 Volume resistivity [Ohm*cm] 120°C, 30min PE-Standard 040 Storage modulus – DMA [MPa] 120°C, 30min 120 – 370		<1
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PE-Standard 009 Coefficient of thermal expansion [ppm/K] below Tg 120°C, 30min PE-Standard 017 Coefficient of thermal expansion [ppm/K] above Tg 120°C, 30min PE-Standard 017 Thermal conductivity [W/m*K] 120°C, 30min 4 - 5 PE-Standard 062 Volume resistivity [Ohm*cm] 120°C, 30min 1 x 10°4 - 3 x 10°4 PE-Standard 040 Storage modulus – DMA [MPa] 120°C, 30min 120 - 370	Glass transition temperature - DSC [°C]	
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120°C, 30min PE-Standard 017 Coefficient of thermal expansion [ppm/K] above Tg 120°C, 30min PE-Standard 017 Thermal conductivity [W/m*K] 120°C, 30min PE-Standard 062 Volume resistivity [Ohm*cm] 120°C, 30min 1 x 10°4 – 3 x 10°4 PE-Standard 040 Storage modulus – DMA [MPa] 120°C, 30min 120 – 370		
PE-Standard 017 Coefficient of thermal expansion [ppm/K] above Tg 120°C, 30min PE-Standard 017 Thermal conductivity [W/m*K] 120°C, 30min PE-Standard 062 Volume resistivity [Ohm*cm] 120°C, 30min PE-Standard 040 Storage modulus – DMA [MPa] 120°C, 30min 120 – 370		
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120°C, 30min PE-Standard 017 Thermal conductivity [W/m*K] 120°C, 30min PE-Standard 062 Volume resistivity [Ohm*cm] 120°C, 30min PE-Standard 040 Storage modulus – DMA [MPa] 120°C, 30min 120°C, 30min		
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Thermal conductivity [W/m*K] 120°C, 30min PE-Standard 062 Volume resistivity [Ohm*cm] 120°C, 30min PE-Standard 040 Storage modulus – DMA [MPa] 120°C, 30min 120 – 370		140 – 200
120°C, 30min PE-Standard 062 Volume resistivity [Ohm*cm] 120°C, 30min PE-Standard 040 Storage modulus – DMA [MPa] 120°C, 30min 120 – 370	PE-Standard 017	
PE-Standard 062 Volume resistivity [Ohm*cm] 120°C, 30min PE-Standard 040 Storage modulus – DMA [MPa] 120°C, 30min 120 – 370	Thermal conductivity [W/m*K]	
Volume resistivity [Ohm*cm] 120°C, 30min PE-Standard 040 Storage modulus – DMA [MPa] 120°C, 30min 120 – 370	120°C, 30min	4 – 5
120°C, 30min PE-Standard 040 Storage modulus – DMA [MPa] 120°C, 30min 1 x 10°4 – 3 x 10°4		
Storage modulus – DMA [MPa] 120°C, 30min 120 – 370	·	1 12/1 2 13/1
Storage modulus – DMA [MPa] 120°C, 30min 120 – 370		1 x 10 ⁻⁴ – 3 x 10 ⁻⁴
120°C, 30min 120 – 370	PE-Standard 040	
	Storage modulus – DMA [MPa]	
PE-Standard 022	120°C, 30min	120 – 370
	PE-Standard 022	

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Lap shear strength (PC/PC) [MPa]	
100°C, 60min	4 – 5
PE-Standard 013	
Lap shear strength (FR4/FR4) [MPa]	
100°C, 60min	5-8
PE-Standard 013	

Transport/Storage/Shelf Life

Package type	Transport	Storage	Shelf life*
Syringe/Cartridge	0°C 10°C	0°C 10°C	At delivery
Other packages	0°C – 10°C	0°C – 10°C	min. 6 months max. 12 months

^{*}Store in original, unopened containers!

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Instructions for use

Surface preparation

The surfaces to be bonded should be free of dust, oil, grease, mold release, or other contaminants in order to obtain an optimal and reproducible bond. For cleaning we recommend the cleaner IP® from Panacol, or a solution of Isopropyl Alcohol at 90% or higher concentration. Substrates with low surface energy (e.g. polyethylene, polypropylene) must be pretreated in order to achieve sufficient adhesion.

Application

Our products are supplied ready to use. Depending on the packaging, our adhesives may be dispensed by hand directly from the package, or they can be applied using dispensing systems and automation. Many commercially available valve and controller options are available to ensure accurate and consistent adhesive dispensing. For assistance with dispensing and curing questions, please contact our Applications Engineering department. Adhesive and substrate should not be cold for proper bonding. They must be allowed to warm to room temperature prior to processing. After curing, the adhesive must be allowed to cool to ambient temperature before testing the product's performance. For safety information refer to our Material Safety Data Sheet (MSDS).

Storage

Store uncured product in its original, closed container in a dry location. Any material removed from the original container must not be returned to the container as it could be contaminated. Panacol cannot assume responsibility for products that were improperly stored, contaminated, or repackaged into other containers.

Handling and Clean-up

For safe handling information, consult this product's Material Safety Data Sheet (MSDS) prior to use. Uncured material may be wiped away from surfaces with organic solvents. Do not use solvents to remove material from eyes or skin!

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Disclaimer

The product is free of heavy metals, PFOS and Phthalates and is conform to the current EU-Directive RoHS.

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